



Features and Benefits

• Ultra Low Loss, less than 0.5 dB insertion loss from 55 to 90 GHz

• Ideal thermal performance due to solid copper construction

• Chip interface compatible with automated Au wire bonding

• PCB interface compatible with standard SMT processes

Applications

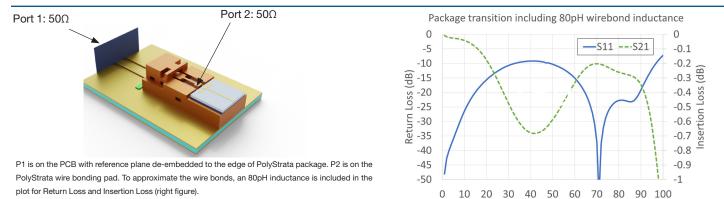
- Military
- Space
- Communications
- Instrumentation



PolyStrata[®] Package: PSP1028106

Market-leading lowest loss, surface mount form factor package for die under 3.71 x 3.55mm up to 90 GHz.

Cubic Nuvotronics presents a new state of the art Low Loss MMIC package. The PolyStrata® package complements integrated MMIC performance, with less than 0.5 dB insertion loss up to 95 GHz and with 12 dB typical return loss. The package can be surface mounted to a PCB using standard SMT processes. This increases the ease of manufacturing while maintaining superior performance in a smaller size compared to other packaging substrates.



Typical Electrical Performance

Frequency (GHz)



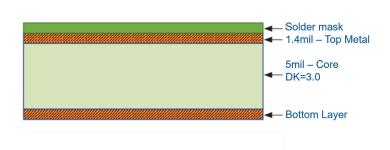
Additional Details

Special Handling / Storage Instructions (Substrate Only)		
Storage	Per JEP160 - Oxygen Sensitive Devices	
ESD Sensitivity	None	
Moisture Sensitivity	Not Applicable	
Component Termination Finish	Immersion Gold over Immersion Silver	
Packaging Available	Gel-Pak [®] , Tape and Reel	
Ordering Part Number	PSP1028106	
Export Classification	EAR99	
Lid Options	Compatible with metal or plastic lids, and most lid-sealing processes	

Absolute Maximum Ratings

Current	2.0 amps
Operating Temp	-55°C to 125°C
Solder Reflow	Compatible with JEDEC J-STD-020
Epoxy Attach	150°C max. for 90 minutes

PCB Stack-up View



Component View

